

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hsien-Cheng Wang</td> <td>03/13/2009</td> </tr> <tr> <td>Hung Chang Hsieh</td> <td>03/13/2009</td> </tr> <tr> <td>Shih-Che Wang</td> <td>03/13/2009</td> </tr> <tr> <td>Ping Chieh Wu</td> <td>03/13/2009</td> </tr> <tr> <td>Wen-Chun Huang</td> <td>03/13/2009</td> </tr> <tr> <td>Ming-Chang Wen</td> <td>03/13/2009</td> </tr> </tbody> </table>		Name	Execution Date	Hsien-Cheng Wang	03/13/2009	Hung Chang Hsieh	03/13/2009	Shih-Che Wang	03/13/2009	Ping Chieh Wu	03/13/2009	Wen-Chun Huang	03/13/2009	Ming-Chang Wen	03/13/2009
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CORRESPONDENCE DATA															
Fax Number:	2142000853														
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
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NAME OF SUBMITTER:

Kelly Gehrke Lyle

Total Attachments: 3

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ASSIGNMENT

WHEREAS, we,

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|-----|------------------|----|--|
| (1) | Hsien-Cheng Wang | of | 13F-1, No. 373, Sec. 2, Gong-Dao 5 Road
Hsinchu 300, Taiwan, R.O.C. |
| (2) | Hung Chang Hsieh | of | 9F, No. 72-12, Lane 531, Sec. 1, Kung-Fu Road
Hsin-Chu City, Taiwan, R.O.C |
| (3) | Shih-Che Wang | of | 4F, No. 8, Lane 634, Nanda Road
Hsin-Chu City, Taiwan, R.O.C. |
| (4) | Ping Chieh Wu | of | 3F, No. 12, Alley 16, Lane 78, Mingyuan Street
Shulin City, Taipei County 238, Taiwan, R.O.C. |
| (5) | Wen-Chun Huang | of | 58, Zhong-Shan Road, Xi-Gang Village
Xi-Gang Xiang, Tainan County 723, Taiwan, R.O.C |
| (6) | Ming-Chang Wen | of | No. 82, Alley 57, Lane 106, Huguang Street, Zuoying District
Kaohsiung City, Taiwan, R.O.C. |

have invented certain improvements in

LITHOGRAPHY METHOD AND APPARATUS FOR SEMICONDUCTOR DEVICE FABRICATION

for which we have executed an application for Letters Patent of the United States of America, on April 2, 2009, as U.S. Serial No. 12/417,090

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect

past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Hsien-Cheng Wang

Residence Address: 13F-1, No. 373, Sec. 2, Gong-Dao 5 Road
Hsinchu 300, Taiwan, R.O.C.

Dated:

Hsien-Cheng Wang
Mar. 13, 2009

Hsien-Cheng Wang
Inventor Signature

Inventor Name: Hung Chang Hsieh

Residence Address: 9F, No. 72-12, Lane 531, Sec. 1, Kung-Fu Road
Hsin-Chu City, Taiwan, R.O.C.

Dated:

✓ Mar. 13, 2009

✓ Hung-Chang Hsieh
Inventor Signature

Inventor Name: Shih-Che Wang

Residence Address: 4F, No. 8, Lane 634, Nanda Road
Hsin Chu City, Taiwan, R.O.C.

Dated:

✓ Mar. 13, 2009

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Inventor Signature

Inventor Name: Ping Chieh Wu

Residence Address: 3F, No. 12, Alley 16, Lane 78, Mingyuan Street
Shulin City, Taipei County 238, Taiwan, R.O.C.

Dated:

✓ Mar. 13, 2009

✓ Ping Chieh Wu
Inventor Signature

Inventor Name: Wen-Chun Huang

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Xi-Gang Xiang, Tainan County 723, Taiwan, R.O.C.

Dated:

✓ Mar. 13, 2009

✓ Wen-Chun Huang
Inventor Signature

Inventor Name: Ming-Chang Wen

Residence Address: No. 82, Alley 57, Lane 106, Huguang Street
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Dated:

✓ Mar. 13, 2009
2009/3/13

✓ 2009/3/13
Inventor Signature